



<b>Title of Change:</b>	Final PCN for wire change from gold to copper and part number change.																																						
<b>Proposed first ship date:</b>	16 September 2015																																						
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com>																																						
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office																																						
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume@onsemi.com>.																																						
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.																																						
<b>Change Part Identification:</b>	Affected products will be identified with new part number (changing suffix to "-W").																																						
	<table border="1"> <thead> <tr> <th>PART_ID</th> <th>New Part_ID</th> </tr> </thead> <tbody> <tr> <td>CPH3455-TL-H</td> <td>CPH3455-TL-W</td> </tr> <tr> <td>MCH6444-TL-H</td> <td>MCH6444-TL-W</td> </tr> </tbody> </table>			PART_ID	New Part_ID	CPH3455-TL-H	CPH3455-TL-W	MCH6444-TL-H	MCH6444-TL-W																														
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<b>Change category(s):</b>	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Product specific change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____																																						
<b>Sites Affected:</b>	<u>Site 1</u>	<u>Site 2</u>																																					
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	ON Shenzhen, China																																						
<b>Description and Purpose:</b>																																							
This is a Final Process Change Notification to announce the content below: 1) Changing wire material from gold to copper 2) Changing part number XXXXXXX-TL-H from XXXXXXX-TL-E																																							
<b>Reliability Data Summary:</b>																																							
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<b>List of Affected Standard Parts:</b>																																							
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